

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Takahiko Ishizu	10/10/2020
Seiichi Yoneda	10/03/2020
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17047740
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	APRIL SAUNDERS-FULLER
SIGNATURE:	/April K. Saunders-Fuller/
DATE SIGNED:	10/15/2020
Total Attachments: 2	
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ASSIGNMENT

For valuable consideration, We, Takahiko ISHIZU of Sagami-hara, Kanagawa, Japan and Seiichi YONEDA of Isehara, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE, filed October 15, 2020, and assigned U.S. Serial Number 17/047,740, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature Takahiko Ishizu
Name: Takahiko ISHIZU
Date: 10/10/2020

Signature _____
Name: Seiichi YONEDA
Date: _____

ASSIGNMENT

For valuable consideration, We, Takahiko ISHIZU of Sagami-hara, Kanagawa, Japan and Seiichi YONEDA of Isehara, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE, filed October 15, 2020, and assigned U.S. Serial Number 17/047,740, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature _____
Name: Takahiko ISHIZU
Date: _____

Signature Seiichi Yoneda
Name: Seiichi YONEDA
Date: 10/03/2020